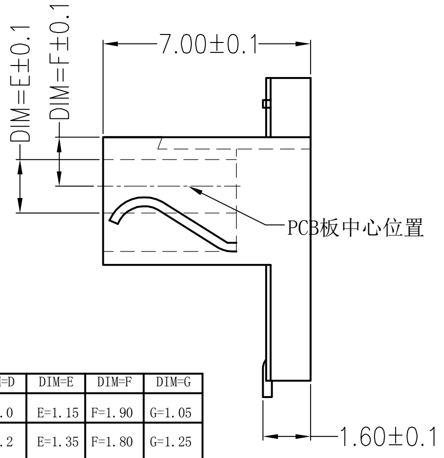
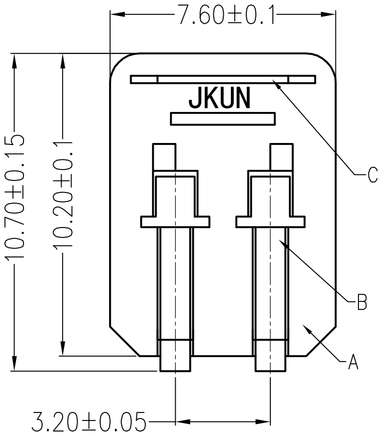
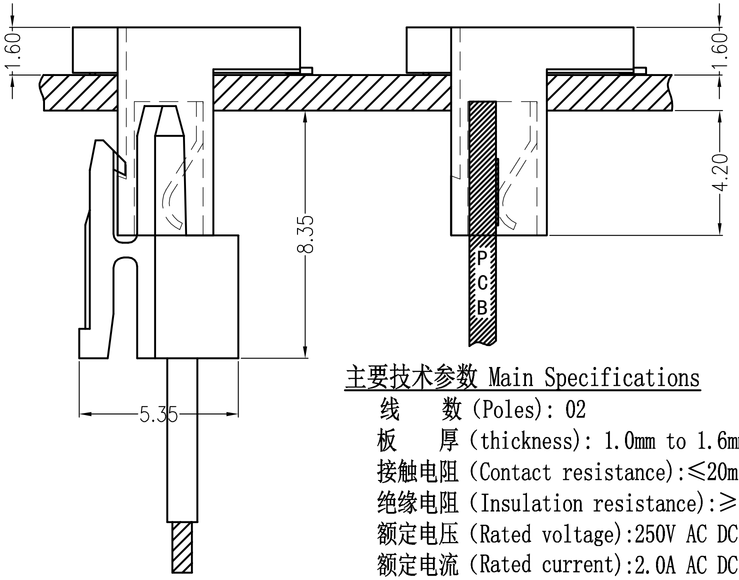
REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2017.03.23

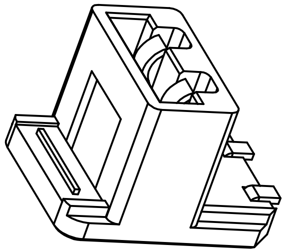


PCB板厚	DIM=D	DIM=E	DIM=F	DIM=G
PCB=1.0	D=1.0	E=1.15	F=1.90	G=1.05
PCB=1.2	D=1.2	E=1.35	F=1.80	G=1.25
PCB=1.6	D=1.6	E=1.75	F=1.60	G=1.65





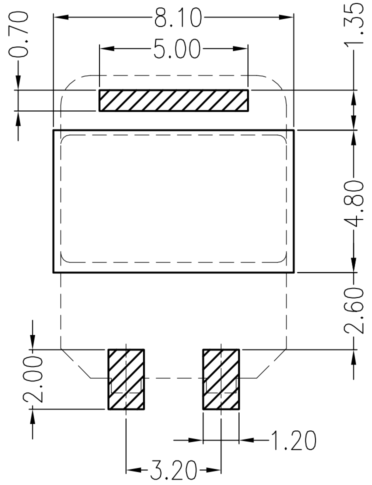
主要技术参数 Main Specifications
线　　数 (Poles): 02
板　　厚 (thickness): 1.0mm to 1.6mm
接触电阻 (Contact resistance):≤20mΩ
绝缘电阻 (Insulation resistance):≥1000MΩ
额定电压 (Rated voltage):250V AC DC
额定电流 (Rated current):2.0A AC DC
耐 电 压 (Withstand Voltage): 1000V AC/minute
温度范围 (Temperature Range) :-25℃～ +105℃



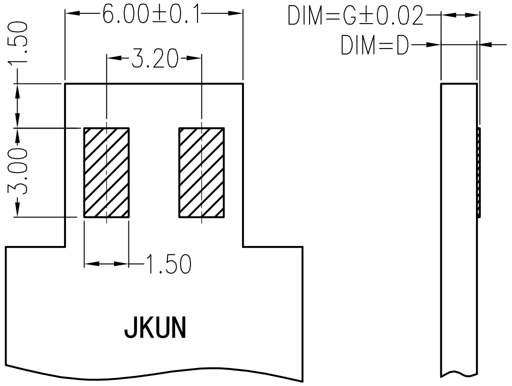
ORDER INFORMATION:

L002-**-F2MB-R

PART No.
No.FOR PCB:
1.0mm/1.2mm/1.6mm
PLASTIC MATERIAL:
F2M=LCP(BEIGE)
PACKAGING:
R=REEL
P=PE
PLATING:
B=MATTE Sn



Board Layout



Mating PCB detail

C	SOLDER TAB		2 PCS	PhosphorBronze	MATTE Sn-plated
B	CONTACT		2 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL		1 PCS	LCP	UL 94V-0, COLOR:BEIGE
ITEM	COMPONENT		Q'TY	MATERIAL	FINISH

JKUN 温 州 健 坤 接 插 件 有 限 公 司
WENZHOU JKUN CONNECTOR CO.,LTD.

TITLE: –
3.2mmPITCH 180°WAFER SMT TYPE

X.±0.5	X.±5°	USE: CUSTOMER	PART NO.: L002-**-F2MB-R
.X±0.3	.X±2°	APPD: 邵敬和	
.XX±0.25	.XX±1°	CHKD: 田 峰	DWG NO.: JKUN/GCCP-0003
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⊕	UNITS: mm	DR: 吴丹平	SCALE 1 : 1 SHEET 1 / 1